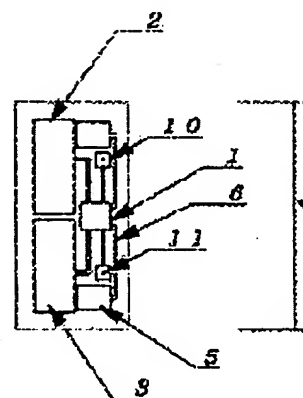


**SUBSTRATE FOR NON-CONTACT IC CARD AND THE NON-CONTACT IC CARD**

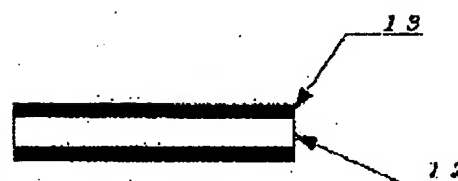
Patent number: JP2002140672  
Publication date: 2002-05-17  
Inventor: SAKATA NAOYUKI; KOBAYASHI KAZUO  
Applicant: TOPPAN PRINTING CO LTD  
Classification:  
- international: G06K19/07; B42D15/10; G06K19/077  
- european:  
Application number: JP20000334252 20001101  
Priority number(s): JP20000334252 20001101

**Abstract of JP2002140672**

**PROBLEM TO BE SOLVED:** To provide a non-contact IC card substrate loaded with capacitors allowed to be formed on a small area, having thickness thinner than an IC chip and high moisture absorption resistance and capable of easily adjusting capacity. **SOLUTION:** Micro-capacitors are used for capacitors 2, 3 to be loaded on a non-contact IC card substrate 4 to be stored in a non-contact IC card base material.



(a)



(b)

Data supplied from the esp@cenet database - Worldwide